

# ABSTRACT

5 A semiconductor encapsulating epoxy resin composition  
comprising (A) an epoxy resin, (B) a phenolic resin curing  
agent, (C) a molybdenum compound, and (D) 300-900 parts by  
weight per 100 parts by weight of components (A) and (B)  
combined of an inorganic filler contains nitrogen atoms in  
an amount of 1.5-20% by weight based on the weight of  
10 components (A) and (B) combined. Cured parts of the  
composition exhibit high-temperature capabilities and flame  
retardance despite the absence of halogenated epoxy resins  
and antimony trioxide.

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